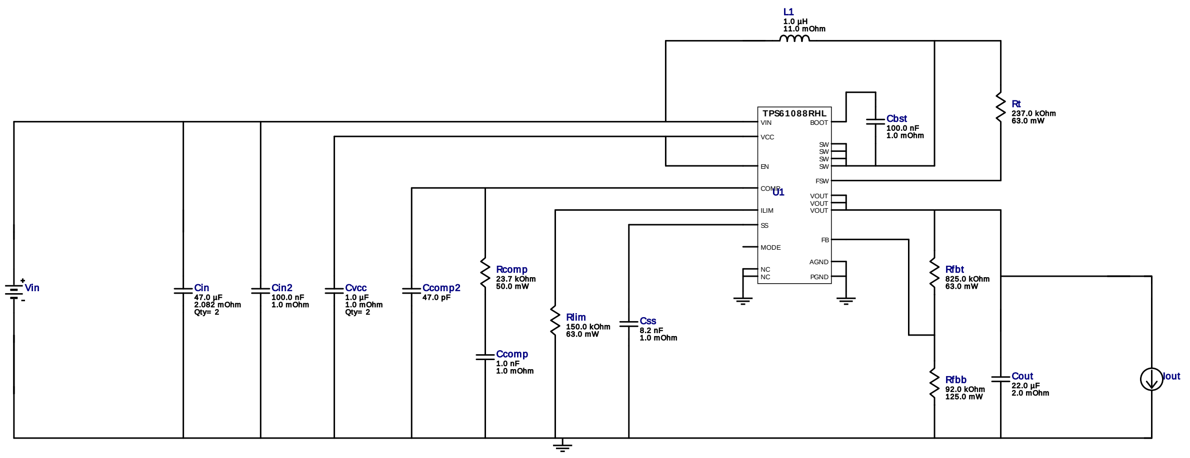
TEXAS INSTRUMENTS

WEBENCH ® Design Report

VinMin = 3.5V
VinMax = 4.2V
Vout = 12.0V
Iout = 1.0A

Device = TPS61088RHLR
Topology = Boost
Created = 2021-03-23 07:13:31.147
BOM Cost = $3.25
BOM Count = 17
Total Pd = 1.68W

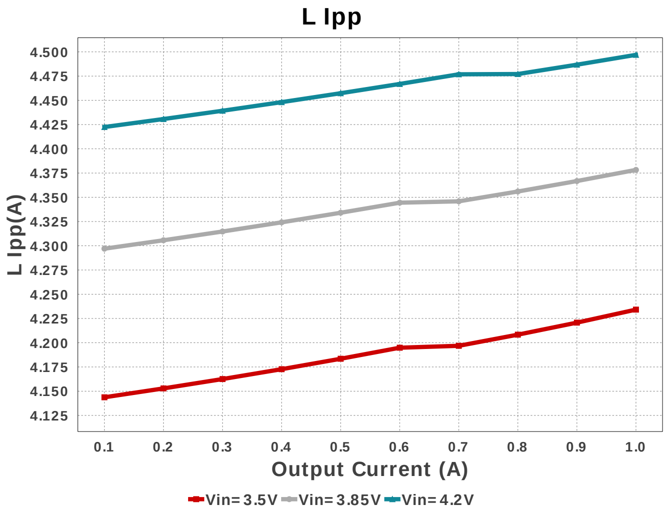
Design : 2 TPS61088RHLR
TPS61088RHLR 3V-4.2V to 9.00V @ 3A

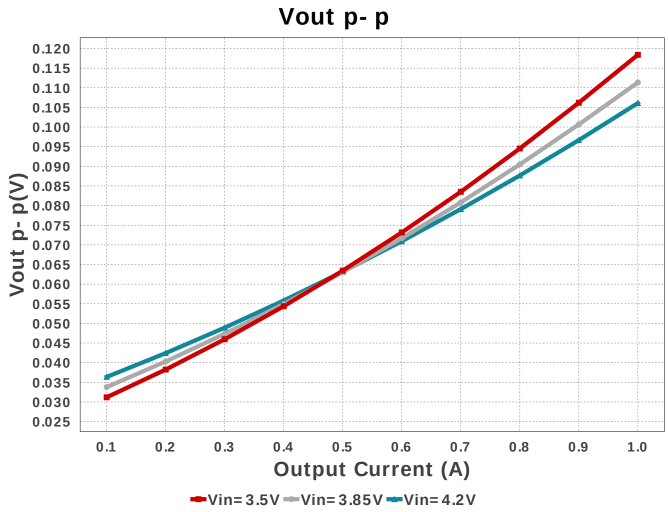


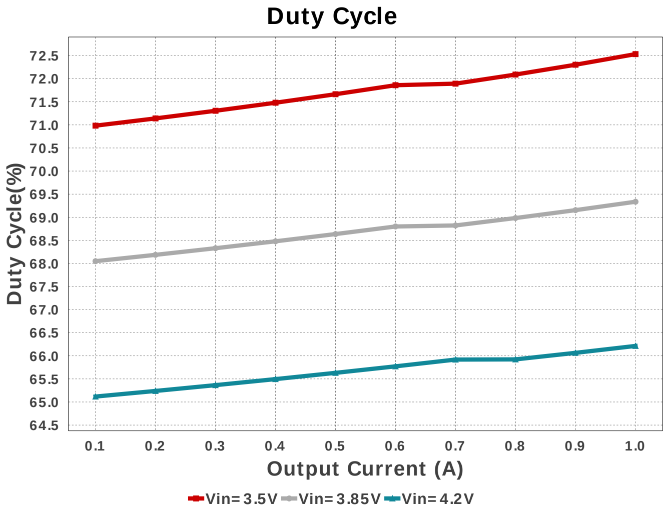
Electrical BOM

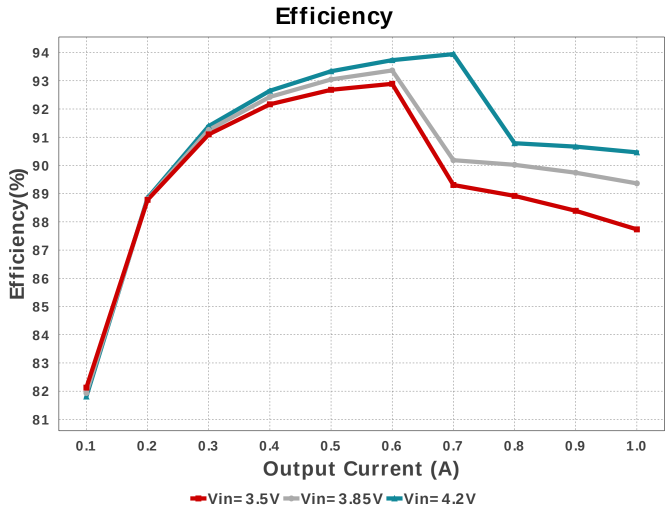
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Ccomp	MuRata	GRM033R71C102KA01D Series= X7R	Cap= 1.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.01	0201 2 mm^2
Ccomp2	MuRata	GRM0335C1E470JA01D Series= C0G/NP0	Cap= 47.0 pF VDC= 25.0 V IRMS= 0.0 A	1	$0.01	0201 2 mm^2
Cin	TDK	C3216X5R1E476M160AC Series= X5R	Cap= 47.0 uF ESR= 2.082 mOhm VDC= 25.0 V IRMS= 5.0279 A	2	$0.39	1206 11 mm^2
Cin2	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cout	MuRata	GRM32ER61E226KE15L Series= X5R	Cap= 22.0 uF ESR= 2.0 mOhm VDC= 25.0 V IRMS= 3.67 A	1	$0.65	1210 15 mm^2
Css	MuRata	GRM155R71C822KA01D Series= X7R	Cap= 8.2 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cvcc	Taiyo Yuden	EMK107B7105KA-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	2	$0.02	0603 5 mm^2
L1	TDK	VLP8040T-1R0N	L= 1.0 µH 11.0 mOhm	1	$0.22	VLP8040 113 mm^2

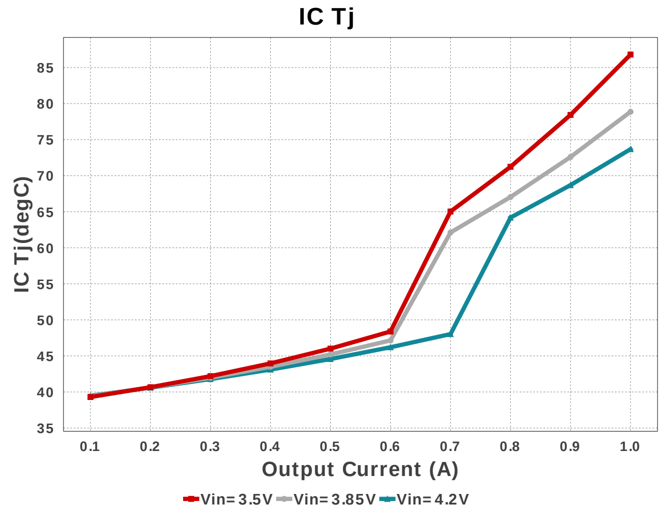
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rcomp	Yageo	RC0201FR-0723K7L Series= ?	Res= 23.7 kOhm Power= 50.0 mW Tolerance= 1.0%	1	$0.01	0201 2 mm^2
Rfbb	Yageo	RT0805BRD0792KL Series= RT0805	Res= 92.0 kOhm Power= 125.0 mW Tolerance= 0.1%	1	$0.06	0805 7 mm^2
Rfbt	Vishay-Dale	CRCW0402825KFKED Series= CRCW..e3	Res= 825.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rlim	Vishay-Dale	CRCW0402150KFKED Series= CRCW..e3	Res= 150.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rt	Vishay-Dale	CRCW0402237KFKED Series= CRCW..e3	Res= 237.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	TPS61088RHLR	Switcher	1	$1.41	RHL0020A 25 mm^2

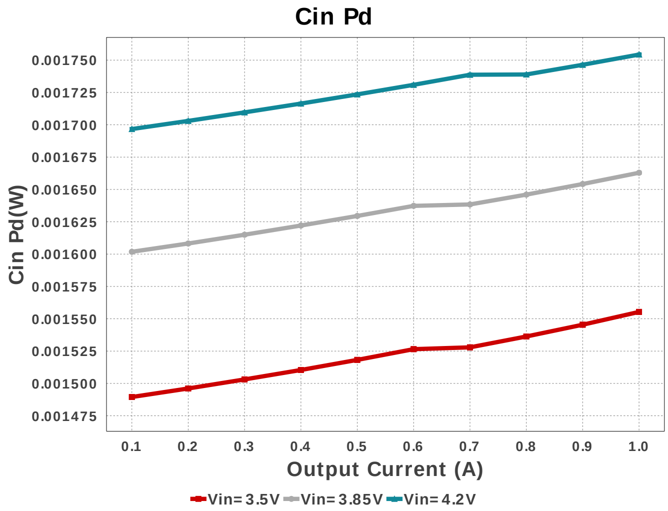


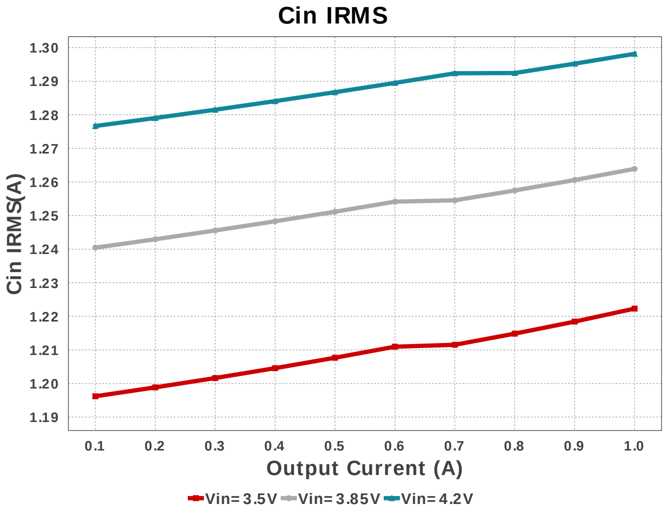


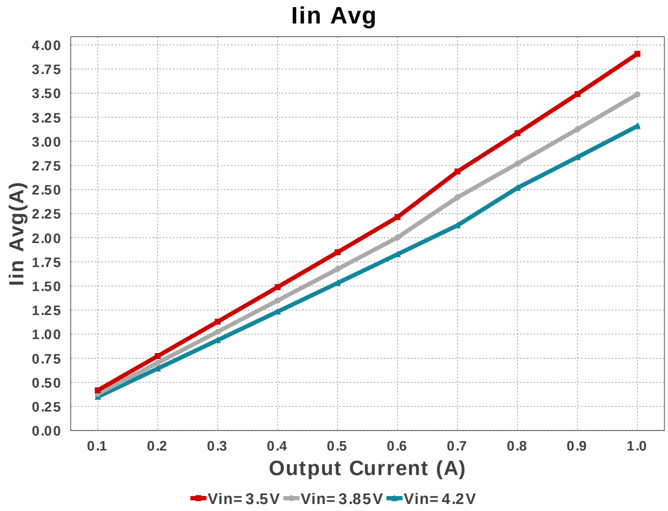


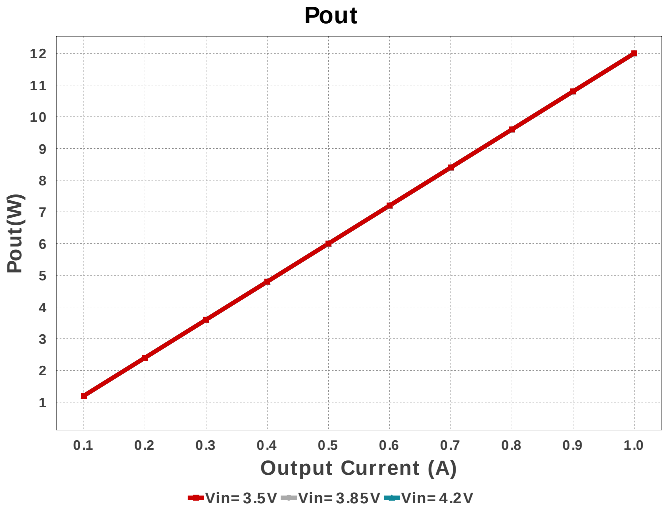


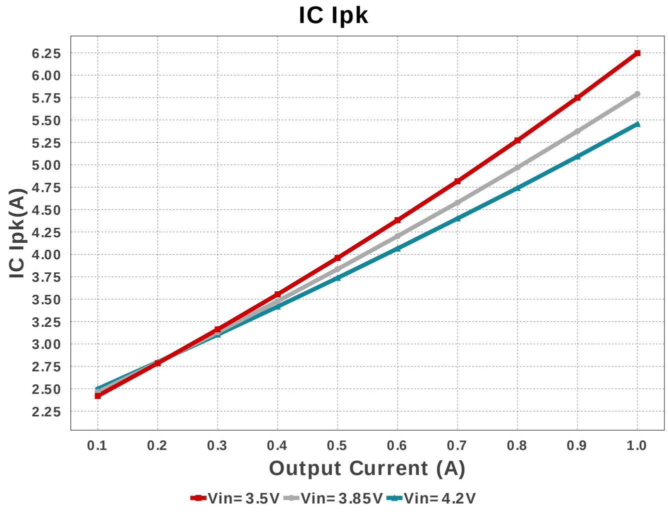

IC Tj
IC Tj(degC)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

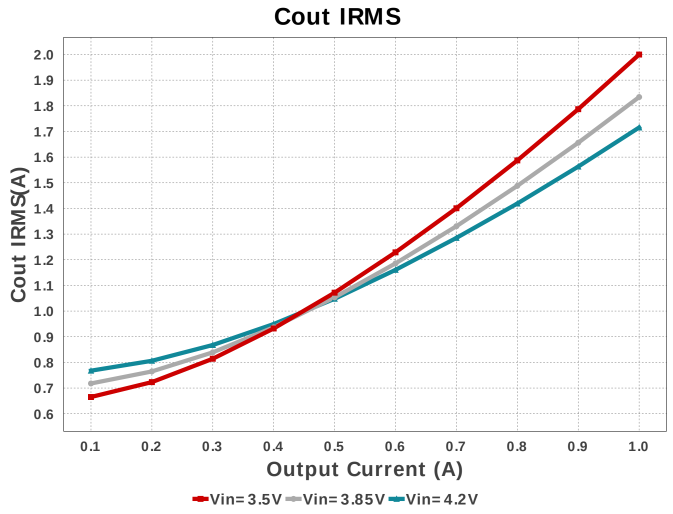

Cin Pd
Cin Pd(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

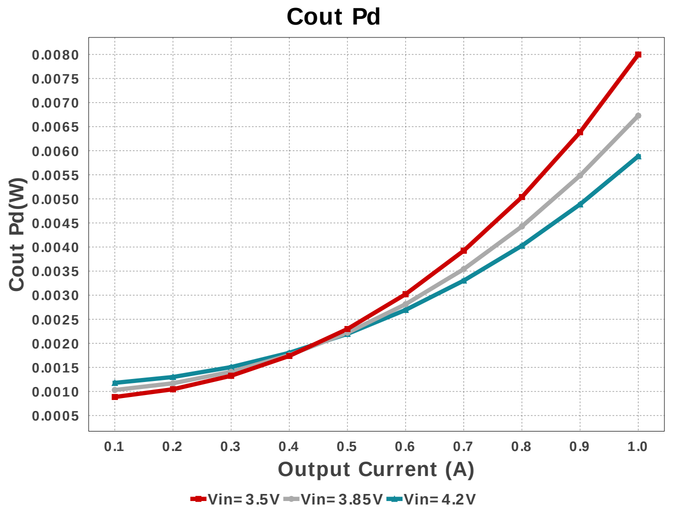

Cin IRMS
Cin IRMS(A)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

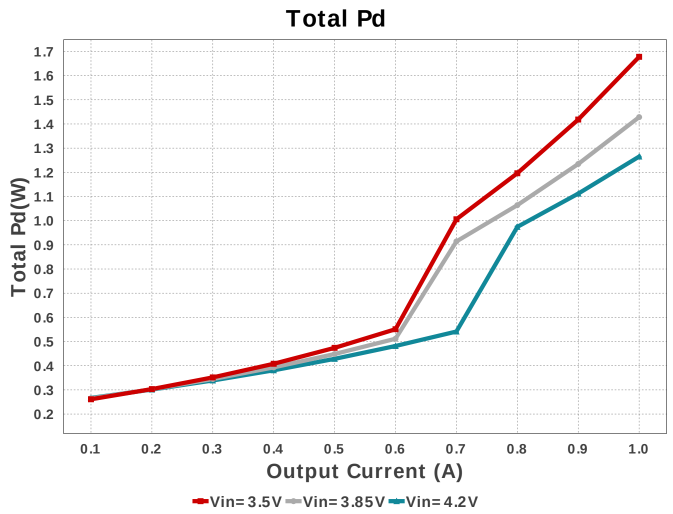

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

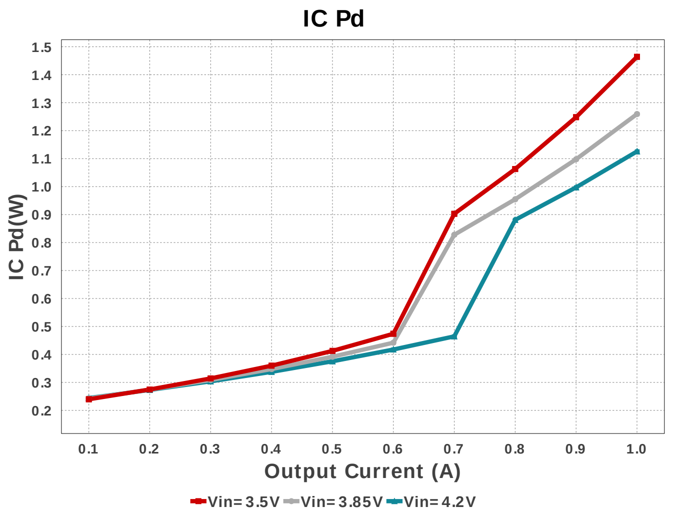

Pout
Pout(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

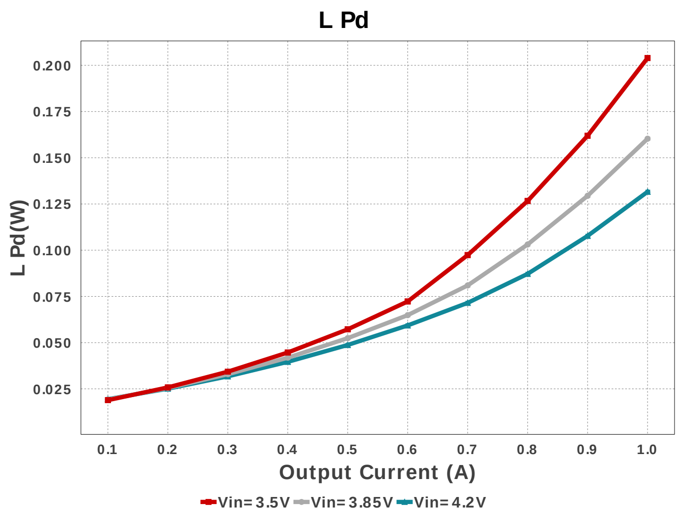

IC Ipk
IC Ipk(A)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

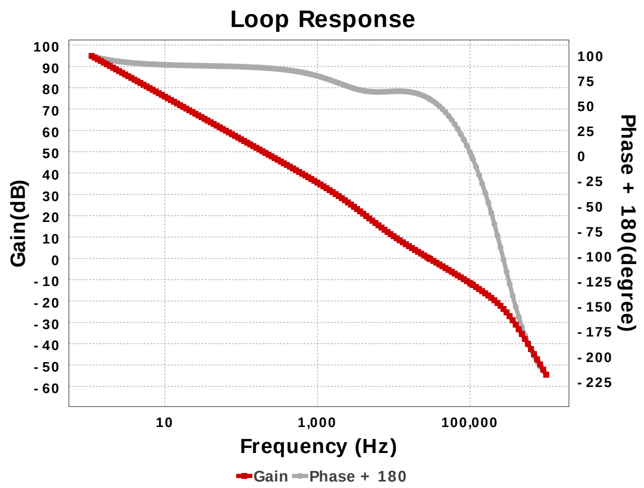

Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V

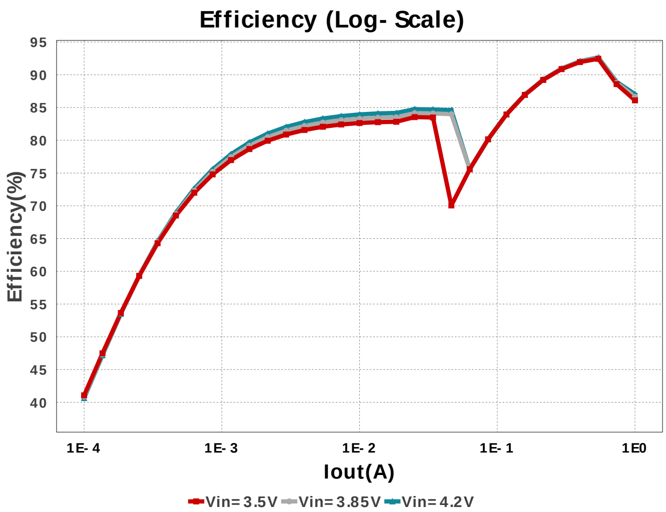

Cout Pd
Cout Pd(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V


Total Pd
Total Pd(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V


IC Pd
IC Pd(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V


L Pd
L Pd(W)
Output Current (A)
Vin=3.5V Vin=3.85V Vin=4.2V


Loop Response
Gain(dB)
Phase + 180(degree)
Frequency (Hz)
Gain Phase + 180



Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	1.222 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	1.555 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	2.0 A	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	7.998 mW	Capacitor	Output capacitor power dissipation
5.	IC Ipk	6.246 A	IC	Peak switch current in IC
6.	IC Pd	1.464 W	IC	IC power dissipation
7.	IC Tj	86.803 degC	IC	IC junction temperature
8.	ICThetaJA	38.8 degC/W	IC	IC junction-to-ambient thermal resistance
9.	Iin Avg	3.908 A	IC	Average input current
10.	L Ipp	4.234 A	Inductor	Peak-to-peak inductor ripple current
11.	L Pd	203.94 mW	Inductor	Inductor power dissipation
12.	Cin Pd	1.555 mW	Power	Input capacitor power dissipation
13.	Cout Pd	7.998 mW	Power	Output capacitor power dissipation
14.	IC Pd	1.464 W	Power	IC power dissipation
15.	L Pd	203.94 mW	Power	Inductor power dissipation
16.	Total Pd	1.678 W	Power	Total Power Dissipation
17.	BOM Count	17	System Information	Total Design BOM count
18.	Cross Freq	28.885 kHz	System Information	Bode plot crossover frequency
19.	Duty Cycle	72.532 %	System Information	Duty cycle
20.	Efficiency	87.734 %	System Information	Steady state efficiency
21.	FootPrint	215.0 mm^2	System Information	Total Foot Print Area of BOM components
22.	Frequency	599.559 kHz	System Information	Switching frequency
23.	Gain Marg	-11.934 dB	System Information	Bode Plot Gain Margin
24.	Iout	1.0 A	System Information	Iout operating point
25.	Low Freq Gain	94.589 dB	System Information	Gain at 1Hz
26.	Mode	BOOST CCM	System Information	PWM/PFM Mode
27.	Phase Marg	57.132 deg	System Information	Bode Plot Phase Margin
28.	Pout	12.0 W	System Information	Total output power
29.	Total BOM	$3.25	System Information	Total BOM Cost
30.	Vin	3.5 V	System Information	Vin operating point
31.	Vout Actual	12.001 V	System Information	Vout Actual calculated based on selected voltage divider resistors
32.	Vout Tolerance	3.633 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
33.	Vout p-p	118.382 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	4.2	Maximum input voltage
VinMin	3.5	Minimum input voltage
Vout	12.0	Output Voltage
base_pn	TPS61088	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

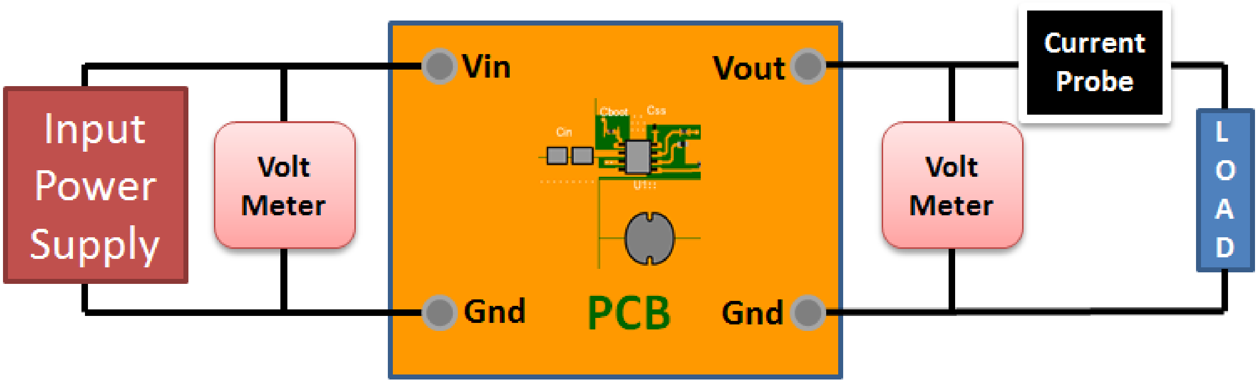
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 3.5V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 49709D4341FDE7D4[v1]

2. **TPS61088** Product Folder : http://www.ti.com/product/TPS61088 : contains the data sheet and other resources.

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